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### FDS3512

### 80V N-Channel PowerTrench® MOSFET

### **General Description**

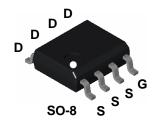
This N-Channel MOSFET has been designed specifically to improve the overall efficiency of DC/DC converters using either synchronous or conventional switching PWM controllers.

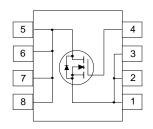
These MOSFETs feature faster switching and lower gate charge than other MOSFETs with comparable  $R_{\text{DS(ON)}}$  specifications.

The result is a MOSFET that is easy and safer to drive (even at very high frequencies), and DC/DC power supply designs with higher overall efficiency.

### **Features**

- 4.0 A, 80 V  $R_{DS(ON)} = 70 \text{ m}\Omega$  @  $V_{GS} = 10 \text{ V}$   $R_{DS(ON)} = 80 \text{ m}\Omega$  @  $V_{GS} = 6 \text{ V}$
- Low gate charge (13nC Typical)
- · Fast switching speed
- High performance trench technology for extremely low R<sub>DS(ON)</sub>
- High power and current handling capability





### Absolute Maximum Ratings TA=25°C unless otherwise noted

Symbol	Parameter		Ratings	Units
V <sub>DSS</sub>	Drain-Source Voltage		80	V
$V_{GSS}$	Gate-Source Voltage		±20	V
I <sub>D</sub>	Drain Current - Continuous	(Note 1a)	4.0	А
	– Pulsed		30	
P <sub>D</sub>	Power Dissipation for Single Operation	(Note 1a)	2.5	W
		(Note 1b)	1.2	
		(Note 1c)	1.0	
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Junction Temperature Range		-55 to +175	°C

### **Thermal Characteristics**

$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	(Note 1a)	50	°C/W
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	(Note 1)	25	°C/W

**Package Marking and Ordering Information** 

Device Marking	Device	Reel Size	Tape width	Quantity
FDS3512	FDS3512	13"	12mm	2500 units

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Drain-Sc	ource Avalanche Ratings (Not	e 2)	· I			ı
W <sub>DSS</sub>	Single Pulse Drain-Source Avalanche Energy	$V_{DD} = 40 \text{ V},  I_{D} = 4.0 \text{ A}$			90	mJ
I <sub>AR</sub>	Maximum Drain-Source Avalanche Current				4.0	Α
Off Char	acteristics					
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V},  I_{D} = 250 \mu\text{A}$	80			V
<u>ΔBV<sub>DSS</sub></u> ΔT <sub>J</sub>	Breakdown Voltage Temperature Coefficient	I <sub>D</sub> = 250 μA, Referenced to 25°C		80		mV/°C
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	$V_{DS} = 64 \text{ V},  V_{GS} = 0 \text{ V}$			1	μΑ
I <sub>GSSF</sub>	Gate-Body Leakage, Forward	$V_{GS} = 20 \text{ V},  V_{DS} = 0 \text{ V}$			100	nA
$I_{GSSR}$	Gate-Body Leakage, Reverse	$V_{GS} = -20 \text{ V}, V_{DS} = 0 \text{ V}$			-100	nA
On Char	acteristics (Note 2)					
V <sub>GS(th)n</sub>	Gate Threshold Voltage	$V_{DS} = V_{GS}$ , $I_D = 250 \mu A$	2	2.4	4	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate Threshold Voltage Temperature Coefficient	I <sub>D</sub> = 250 μA, Referenced to 25°C		-6		mV/°C
R <sub>DS(on)</sub>	Static Drain–Source On–Resistance	$\begin{split} &V_{GS} = 10 \text{ V}, & I_D = 4.0 \text{ A} \\ &V_{GS} = 6 \text{ V}, & I_D = 3.7 \text{A} \\ &V_{GS} = 10 \text{ V}, & I_D = 4.0 \text{ A}, T_J = 125 ^{\circ}\text{C} \end{split}$		50 55 91	70 80 135	mΩ
I <sub>D(on)</sub>	On-State Drain Current	$V_{GS} = 10 \text{ V},  V_{DS} = 5 \text{ V}$	20			Α
G <sub>FS</sub>	Forward Transconductance	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 4.0 A		14		S
Dynamic	Characteristics					
C <sub>iss</sub>	Input Capacitance	$V_{DS} = 40 \text{ V},  V_{GS} = 0 \text{ V},$		634		pF
Coss	Output Capacitance	f = 1.0 MHz		58		pF
C <sub>rss</sub>	Reverse Transfer Capacitance			28		pF
Switchir	g Characteristics (Note 2)					
t <sub>d(on)</sub>	Turn-On Delay Time	$V_{DD} = 40 \text{ V},  I_D = 1 \text{ A},$		7	14	ns
t <sub>r</sub>	Turn-On Rise Time	$V_{GS} = 10 \text{ V},  R_{GEN} = 6 \Omega$		3	6	ns
t <sub>d(off)</sub>	Turn-Off Delay Time			24	38	ns
t <sub>f</sub>	Turn-Off Fall Time			4	8	ns
Q <sub>g</sub>	Total Gate Charge	$V_{DS} = 40 \text{ V},  I_{D} = 4.0 \text{ A},$		13	18	nC
$Q_{gs}$	Gate-Source Charge	V <sub>GS</sub> = 10 V		2.4		nC
$Q_{gd}$	Gate-Drain Charge			2.8		nC
Drain-S	ource Diode Characteristics	and Maximum Ratings				
Is	Maximum Continuous Drain-Sourc				2.1	Α
V <sub>SD</sub>	Drain-Source Diode Forward Voltage	$V_{GS} = 0 \text{ V},  I_S = 2.1 \text{ A}$ (Note 2)		0.8	1.2	V

#### Notes

1. R<sub>eJA</sub> is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. R<sub>eJC</sub> is guaranteed by design while R<sub>eCA</sub> is determined by the user's board design.



a) 50 °C/W when mounted on a 1in² pad of 2 oz copper



b) 105 °C/W when mounted on a 0.04 in² pad of 2 oz copper



c) 125 °C/W when mounted on a minimum pad.

2. Pulse Test: Pulse Width < 300µs, Duty Cycle < 2.0%

### **Typical Characteristics**

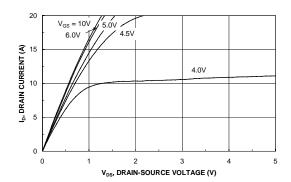


Figure 1. On-Region Characteristics.

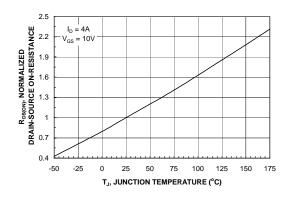


Figure 3. On-Resistance Variation with Temperature.

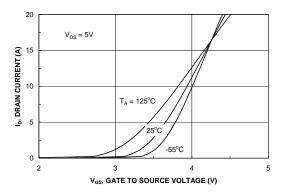


Figure 5. Transfer Characteristics.

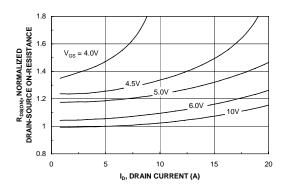


Figure 2. On-Resistance Variation with Drain Current and Gate Voltage.

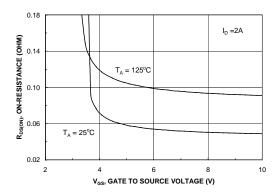


Figure 4. On-Resistance Variation with Gate-to-Source Voltage.

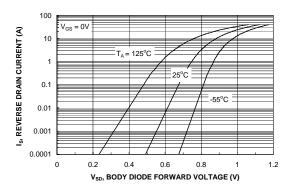
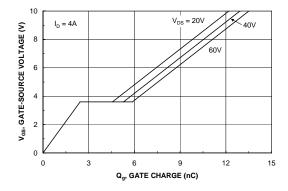


Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature.

### **Typical Characteristics**



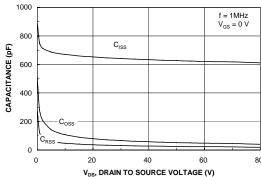


Figure 7. Gate Charge Characteristics.

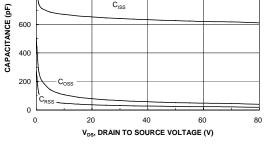
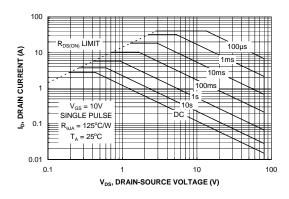


Figure 8. Capacitance Characteristics.



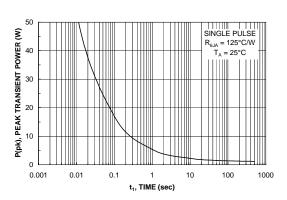


Figure 9. Maximum Safe Operating Area.

Figure 10. Single Pulse Maximum Power Dissipation.

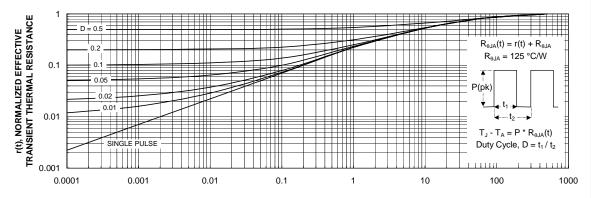


Figure 11. Transient Thermal Response Curve.

Thermal characterization performed using the conditions described in Note 1c. Transient thermal response will change depending on the circuit board design.

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